

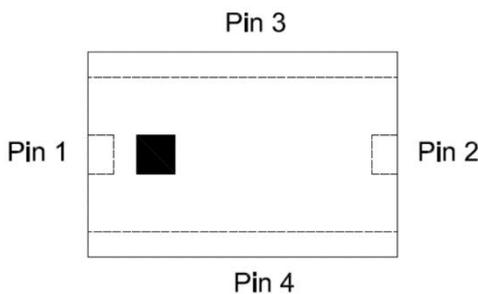
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

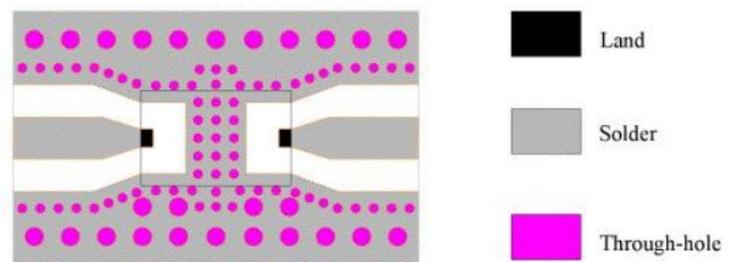
NO.	Parameter	Frequency (MHz)	SPEC	
			Min.	Max.
1	Insertion Loss (dB)	2565~2585		4.0
2	Attenuation (dB)	165~185	60	
		330~1815	30	
		1815~1835	35	
		1835~2070	30	
		2400	20	
		2730~2770	20	
		4060~5540	40	
	6645~7755	30		
3	Ripple(dB)	2565~2585		0.3
4	In/Output Impedance (Ω)		50	
5	Max Input Power		34dBm	

Construction



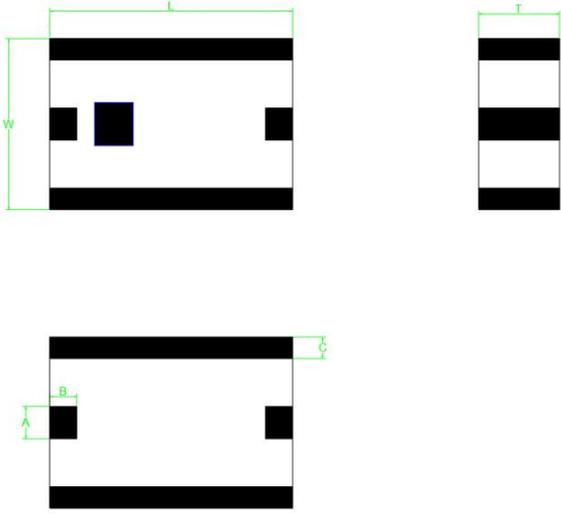
PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

Mounting Considerations

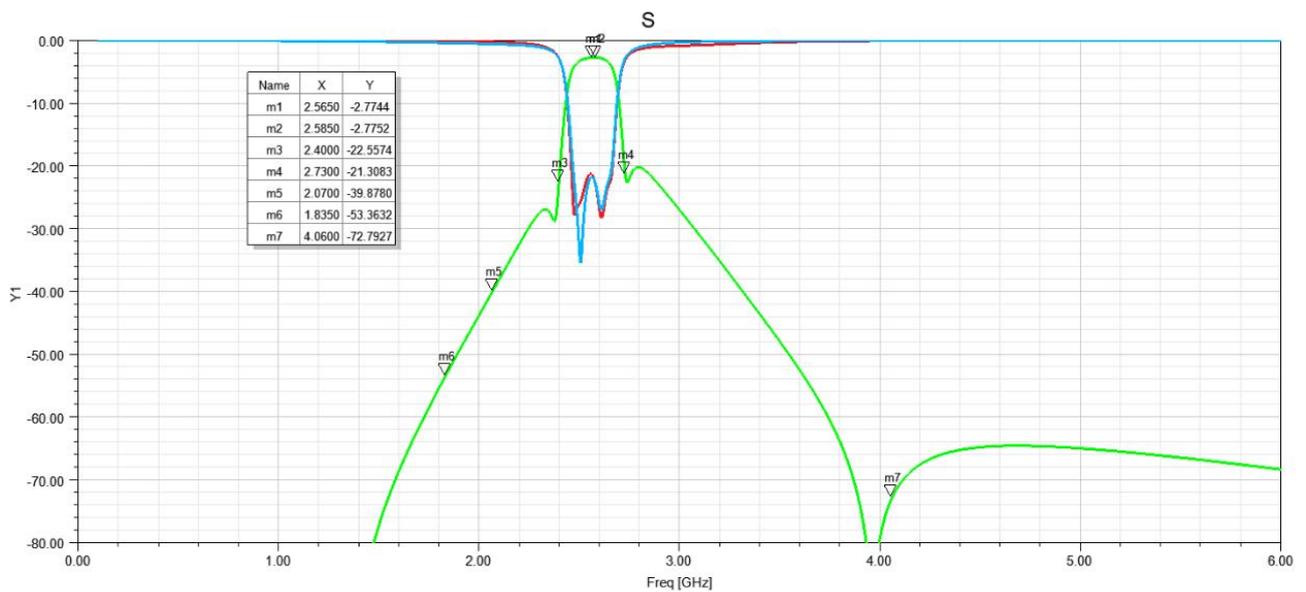


Unit: mm
 Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
	L	4.50±0.20
	W	3.20±0.20
	T	1.50±0.20
	A	0.60±0.10
	B	0.50±0.10
	C	0.40±0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.